

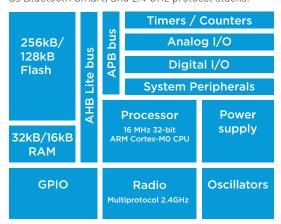


# nRF51822

Multiprotocol Bluetooth low energy and 2.4GHz proprietary System-on-Chip

# **ULP wireless System-on-Chip**

The nRF51822 is a powerful multiprotocol single chip solution for ULP wireless applications. It incorporates Nordic's latest best-in-class performance radio transceiver, an ARM® Cortex™ M0 CPU and 256kB/128kB flash and 32kB/16kB RAM memory. The nRF51822 supports *Bluetooth*® low energy (formerly known as Bluetooth Smart) and 2.4 GHz protocol stacks.



# Lower power and higher performance

The nRF51822 uses the 32-bit ARM Cortex M0 MCU, together with extensive flash availability, 256kB/128kB in total with 40kB-180kB available for application development. Code density and execution speed are considerably greater than for 8/16-bit platforms. The Programmable Peripheral Interconnect (PPI) system provides a 16-channel bus for direct and autonomous system peripheral communication without CPU intervention. This brings predictable latency times for peripheral to peripheral interaction and power saving benefits associated with leaving the CPU idle. The device has 2 global power modes ON/OFF, but all system blocks and peripherals have individual power management control which allows for an automatic switching RUN/IDLE for system blocks based only on those required/not required to achieve particular tasks.

The new radio forms the basis of the nRF51822's performance. The radio supports Bluetooth low energy and is on air compatible with the nRF24L Series products from Nordic Semiconductor. Output power is now scalable from a maximum of +4dBm down to -20dBm in 4dB steps. Sensitivity is increased at every level and offers sensitivity ranges (dependent on data rate) from -96 to -85dBm, with -93dBm for Bluetooth low energy.

#### **KEY FEATURES**

- Multiprotocol 2.4GHz radio
- 32-bit ARM Cortex M0 processor
- 256kB/128kB flash and 32kB/16kB RAM
- Software stacks available as downloads
- Pin compatible with other nRF51 Series devices
- Application development independent from protocol stack
- Fully on-air compatible with nRF24L Series
- Programmable output power from +4dBm to -20dBm
- RSSI
- RAM mapped FIFOs using EasyDMA
- Dynamic on air payload length up to 256 Bytes
- Flexible and configurable 31 pin GPIO
- Programmable Peripheral Interface PPI
- Simple ON/OFF global power modes
- Full set of digital interfaces including: SPI/2-wire/UART
- 10-bit ADC
- 128-bit AES ECB/CCM/AAR co-processor
- Quadrature demodulator
- Low cost external crystal 16MHz ± 40ppm
- Low power 16MHz crystal and RC oscillators
- Ultra low power 32kHz crystal and RC oscillators
- Wide supply voltage range (1.8 V to 3.6 V)
- On-chip DC/DC buck converter
- Individual power management for all peripherals
- Package options: 48-pin 6x6 QFN/WLCSP, Thin-CSP

# **APPLICATIONS**

- Bluetooth low energy applications
- Wearables
- Beacons
- Appcessories
- Computer peripherals
- CE remote controls for TV, STB and media systems
- Proximity and security alert tags
- Sports- and fitness sensors
- Healthcare and lifestyle sensors
- Game controllers for computers
- Toys and Electronic games
- Domestic/Industrial control and data-acquisition
- Intelligent domestic appliances

### Easy, fast and safe code development

The nRF51822 offers developers a clean separation between application code development and embedded protocol stacks. This means compile, link and run-time dependencies with the embedded stack and associated de-bugging challenges are removed. The Bluetooth low energy stack is a pre-compiled binary available from Nordic Semiconductor, leaving application code to be compiled stand-alone. The embedded stack interface uses an asynchronous and event-driven model removing the need for RTOS frameworks.

#### **OTA DFU**

The nRF51822 is supported by a Over The Air Device Firmware Upgrade (OTA-DFU) feature. This allows for in the field updates of application software and SoftDevices.

# Maximum re-use and easy migration

The devices in the nRF51 Series are pin compatible enabling migration between technologies such as Bluetooth low energy and ANT with no layout changes. The common HW architecture ensures that one codebase can be re-used effortlessly between nRF51 Series devices. Variants in the nRF51 Series enable simple choices tailoring device selection to desired wireless protocol and feature requirements with little or no changes.

# Application code Bluetooth low energy Protocol Stack SoC

#### **SoftDevices**

The Nordic protocol stacks are known as SoftDevices and complement the nRF51 Series SoCs. All nRF51 Series are programmable with software stacks available from Nordic Semiconductor. This brings maximum flexibility to application development and allows the latest stack version to be programmed into the nRF51 Series SoC.

#### nRF51822 compatible SoftDevices

S130	Bluetooth low energy concurrent central/ peripheral/observer/broadcaster stack	
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# Development tools

Nordic Semiconductor provides a complete range of hardware and software development tools for the nRF51 Series devices.

#### **RELATED PRODUCTS**

nRF51 DK	Development kit for Bluetooth low energy, ANT and 2.4GHz applications
nRF51 Dongle	Bluetooth low energy/ANT/2.4GHz development dongle
nRF51422	ANT/Bluetooth low energy multiprotocol SoC

#### **SPECIFICATIONS**

Frequency band 2.4GHz ISM ( 2.40000 – 2.4835GHz)  On-air data rate 250 kbps, 1 Mbps or 2 Mbps  Modulation GFSK  Output power Programmable: +4 to -20dBm in 4dB steps  Sensitivity -93dBm Bluetooth low energy -96dBm at 250kb -90dBm at 1250kb -90dBm at 1 Mbs -85dBm at 27Mbs  Radio current consumption LDO at 1.8V 16.5mA – TX at +4dBM output power 13.5mA – TX at 1 0dBm output power 13.5mA – TX at 1 0dBm output power 8.06mA – TX at 1 dbBm output power 9.7mA – RX at 1 Mbs  Radio current consumption B.06mA – TX at 0dBm output power 9.7mA – RX at 1 Mbs  Radio current consumption 256kB/128kB Flash Oscillator 32-bit ARM Cortex M0  Program Memory 256kB/128kB Flash  RAM 32kB/16kB  Oscillators 16MHz crystal oscillator 16MHz RC oscillator 32kHz crystal oscillator 12xHz crystal oscillator 12xHz RC oscillator 12x		
Modulation  GFSK  Output power  Programmable: +4 to -20dBm in 4dB steps  Sensitivity  -93dBm Bluetooth low energy -94dBm at 250kb -90dBm at 1Mbs -85dBm at 2Mbs  Radio current consumption LD0 at 1.8V  10.5mA - TX at +4dBm output power 13mA - RX at 1Mbs  Radio current consumption DC-DC at 3V  Robres - TX at +4dBm output power 8.06mA - TX at 0dBm output power 9.7mA - RX at 1Mbs  Microcontroller  32-bit ARM Cortex M0  Program Memory  256kB/128kB Flash  RAM  32kB/16kB  Oscillators  16MHz crystal oscillator 16MHz RC oscillator 32kHz crystal oscillator 32kHz RC oscil	Frequency band	2.4GHz ISM ( 2.40000 – 2.4835GHz)
Output power Programmable: +4 to -20dBm in 4dB steps  Sensitivity -93dBm Bluetooth low energy -96dBm at 250kb -90dBm at 250kb -90dBm at 1Mbs -85dBm at 2Mbs  Radio current consumption LDO at 1.8V 10.5mA - TX at +4dBM output power 10.5mA - TX at 0dBm output power 13mA - RX at 1Mbs  Radio current consumption 2.05mA - TX at 1.4dBm output power 8.06mA - TX at 1.4dBm output power 9.7mA - RX at 1Mbs  Microcontroller 32-bit ARM Cortex M0  Program Memory 256kB/128kB Flash  RAM 32kB/16kB  Oscillators 16MHz crystal oscillator 16MHz RC oscillator 32kHz RC oscillator 4.6µA - No RAM retention 1.2µA - 8k RAM retention 1.2µA - 8k RAM retention 1.2µA - 8k RAM retention 2.6µA - All peripherals in IDLE mode  Hardware Security 128-bit AES ECB/CCM/AAR co-processor  GPIO 31 configurable  Digital I/O X2 Hardware SPI master 2X 2-wire master UART Quadrature demodulator  Peripherals 10-bit ADC RNG Temperature sensor RTC  PPI 16-channel  Voltage regulator LDO (1.8 to 3.6V), LDO bypass (1.75 to 1.75V) Buck DC/DC (2.1 to 3.6V)  Timers/counters 2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC  Package options ROHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	On-air data rate	250 kbps, 1 Mbps or 2 Mbps
Sensitivity -93dBm Bluetooth low energy -96dBm at 250kb -90dBm at 1Mbs -85dBm at 250kb -90dBm at 1Mbs -85dBm at 250kb -90dBm at 1Mbs -85dBm at 2Mbs  Radio current consumption LDO at 1.8V  10.5mA - TX at +4dBM output power 10.5mA - TX at 1Mbs  Radio current consumption DC-DC at 3V  10.5mA - TX at 1Mbs  Ricrocontroller  32-bit ARM Cortex M0  Program Memory  256kB/128kB Flash  RAM  32kB/16kB  Oscillators  16MHz crystal oscillator 16MHz RC oscillator 32kHz crystal oscillator 32kHz RC o	Modulation	GFSK
-96dBm at 250kb -90dBm at 1Mbs -85dBm at 2Mbs  Radio current consumption LD0 at 1.8V  Radio current consumption LD0 at 1.8V  Radio current consumption BC-DC at 3V  Radio current Consumption Coscillator BC-DC at 3V  Radio Corrent Coscillator BC-DC at 3V  Radio Corrent Consumption Coscillator BC-DC Complete Consumption Coscillator BC-DC Complete Consumption Coscillator BC-DC Complete Co	Output power	Programmable: +4 to -20dBm in 4dB steps
sumption LD0 at 1.8V         10.5mA – TX at 0dBm output power 13mA – RX at 1Mbs         Radio current consumption B.06mA – TX at 1dBm output power 8.06mA – TX at 1dBm output power 9.7mA – RX at 1Mbs         Microcontroller         32-bit ARM Cortex M0         Program Memory         256kB/128kB Flash         RAM         32kB/16kB         Oscillator 32kHz RC oscillator 16MHz RC oscillator 32kHz RC oscillator 32kHz RC oscillator 32kHz RC oscillator 4250 ppm)         System current consumption       0.6μA – No RAM retention 1.2μA – 8k RAM retention 2.6μA – All peripherals in IDLE mode         Hardware Security       128-bit AES ECB/CCM/AAR co-processor         GPIO       31 configurable         Digital I/O       X2 Hardware SPI master 2X 2-wire master UART Quadrature demodulator         Peripherals       10-bit ADC RNG Temperature sensor RTC         PPI       16-channel         Voltage regulator       LD0 (1.8 to 3.6V), LD0 bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V)         LD0 (1.8 to 3.6V), LD0 bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V) Timers/counters         Package options	Sensitivity	-96dBm at 250kb -90dBm at 1Mbs
consumption DC-DC at 3V 9.7mA – TX at 0dBm output power 9.7mA – RX at 1Mbs  Microcontroller 32-bit ARM Cortex M0  Program Memory 256kB/128kB Flash  RAM 32kB/16kB  Oscillators 16MHz crystal oscillator 16MHz RC oscillator 32kHz Crystal oscillator 32kHz RC oscillator 32kHz RC oscillator 1.2pA – 8k RAM retention 1.2pA – 8k RAM retention 2.6pA – All peripherals in IDLE mode  Hardware Security 128-bit AES ECB/CCM/AAR co-processor  GPIO 31 configurable  Digital I/O X2 Hardware SPI master 2X 2-wire master UART Quadrature demodulator  Peripherals 10-bit ADC RNG Temperature sensor RTC  PPI 16-channel  Voltage regulator LDO (1.8 to 3.6V), LDO bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V)  Timers/counters 2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC  Package options ROHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),		10.5mA – TX at 0dBm output power
Program Memory       256kB/128kB Flash         RAM       32kB/16kB         Oscillators       16MHz crystal oscillator 32kHz crystal oscillator 32kHz RC oscillator 32kHz RC oscillator (±250 ppm)         System current consumption       0.6μA – No RAM retention 1.2μA – 8k RAM retention 2.6μA – All peripherals in IDLE mode         Hardware Security       128-bit AES ECB/CCM/AAR co-processor         GPIO       31 configurable         Digital I/O       X2 Hardware SPI master 2X 2-wire master UART Quadrature demodulator         Peripherals       10-bit ADC RNG Temperature sensor RTC         PPI       16-channel         Voltage regulator       LDO (1.8 to 3.6V), LDO bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V)         Timers/counters       2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC         Package options       RoHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	consumption	8.06mA – TX at 0dBm output power
RAM  Oscillators  16MHz crystal oscillator 16MHz RC oscillator 32kHz crystal oscillator 32kHz RC oscillator 4250 ppm)  System current consumption  0.6μA – No RAM retention 1.2μA – 8k RAM retention 2.6μA – All peripherals in IDLE mode  Hardware Security  128-bit AES ECB/CCM/AAR co-processor  GPIO  31 configurable  X2 Hardware SPI master 2X 2-wire master UART Quadrature demodulator  Peripherals  10-bit ADC RNG Temperature sensor RTC  PPI  16-channel  Voltage regulator  LDO (1.8 to 3.6V), LDO bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V)  Timers/counters  2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC  Package options  RoHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	Microcontroller	32-bit ARM Cortex M0
Oscillators  16MHz crystal oscillator 16MHz RC oscillator 32kHz crystal oscillator 32kHz RC oscillator 428 RAM retention 1.2μA - 8k RAM retention 2.6μA - All peripherals in IDLE mode  Hardware Security  128-bit AES ECB/CCM/AAR co-processor  GPIO  31 configurable  Digital I/O  X2 Hardware SPI master 2X 2-wire master UART Quadrature demodulator  Peripherals  10-bit ADC RNG Temperature sensor RTC  PPI  16-channel  Voltage regulator  LDO (1.8 to 3.6V), LDO bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V)  Timers/counters  2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC  Package options  RoHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	Program Memory	256kB/128kB Flash
16MHz RC oscillator 32kHz crystal oscillator 32kHz crystal oscillator 32kHz RC oscillator (±250 ppm)  System current consumption  0.6μA – No RAM retention 1.2μA – 8k RAM retention 2.6μA – All peripherals in IDLE mode  Hardware Security  128-bit AES ECB/CCM/AAR co-processor  GPIO  31 configurable  Digital I/O  X2 Hardware SPI master 2X 2-wire master UART Quadrature demodulator  Peripherals  10-bit ADC RNG Temperature sensor RTC  PPI  16-channel  Voltage regulator  LDO (1.8 to 3.6V), LDO bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V) Timers/counters  2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC  Package options  RoHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	RAM	32kB/16kB
consumption       1.2μA - 8k RAM retention         2.6μA - All peripherals in IDLE mode         Hardware Security       128-bit AES ECB/CCM/AAR co-processor         GPIO       31 configurable         Digital I/O       X2 Hardware SPI master         2X 2-wire master       UART         Quadrature demodulator         Peripherals       10-bit ADC         RNG       Temperature sensor         RTC         PPI       16-channel         Voltage regulator       LDO (1.8 to 3.6V),         LDO bypass (1.75 to 1.95V)       Buck DC/DC (2.1 to 3.6V)         Timers/counters       2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC         Package options       RoHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	Oscillators	16MHz RC oscillator 32kHz crystal oscillator
GPIO 31 configurable  Digital I/O X2 Hardware SPI master 2X 2-wire master UART Quadrature demodulator  Peripherals 10-bit ADC RNG Temperature sensor RTC  PPI 16-channel  Voltage regulator LDO (1.8 to 3.6V), LDO bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V)  Timers/counters 2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC  Package options ROHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	,	1.2µA - 8k RAM retention
Digital I/O  X2 Hardware SPI master 2X 2-wire master UART Quadrature demodulator  Peripherals  10-bit ADC RNG Temperature sensor RTC  PPI  16-channel  Voltage regulator  LDO (1.8 to 3.6V), LDO bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V)  Timers/counters  2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC  Package options  RoHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	Hardware Security	128-bit AES ECB/CCM/AAR co-processor
2X 2-wire master UART Quadrature demodulator  Peripherals  10-bit ADC RNG Temperature sensor RTC  PPI  16-channel  Voltage regulator  LD0 (1.8 to 3.6V), LD0 bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V) Timers/counters  2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC  Package options  RoHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	GPI0	31 configurable
RNG Temperature sensor RTC  PPI 16-channel  Voltage regulator LDO (1.8 to 3.6V), LDO bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V)  Timers/counters 2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC  Package options RoHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	Digital I/O	2X 2-wire master UART
Voltage regulator  LDO (1.8 to 3.6V), LDO bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V)  Timers/counters  2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC  Package options  RoHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	Peripherals	RNG Temperature sensor
LD0 bypass (1.75 to 1.95V) Buck DC/DC (2.1 to 3.6V)  Timers/counters 2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC  Package options RoHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	PPI	16-channel
Package options  RoHS compliant 48-pin 6x6 QFN / 3 Ultra-compact Wafer Level Chip Scale Package options (WLCSP),	Voltage regulator	LDO bypass (1.75 to 1.95V)
Wafer Level Chip Scale Package options (WLCSP),	Timers/counters	2 x 16 bit, 1 x 24bit, 2 x 24bit, RTC
	Package options	Wafer Level Chip Scale Package options (WLCSP),

